

12th International Conference on Microwave Materials and their Applications

Call for Papers

Abstract submission open until June 15, 2023 Register under <http://mma2023.uni-mainz.de>

Keynote Speakers



Malgorzata Celuch

President QWED, Warsaw, Poland

Recent Developments
and Cross-Calibration
of Resonator-Based Techniques
for Microwave
and mmWave Materials Assessment



Madhavan Swaminathan

Dept. Head Electrical Engineering,
Director, CHIMES (an SRC JUMP 2.0 Center)
Penn State University, PA, USA

Packaging Materials for Advanced
Computing and Communications -
Challenges and Opportunities



Yasutaka Sugimoto

Principal Researcher RF development,
Murata Manufacturing, Kyoto, Japan

LTCC materials
and their processes
for wireless communications

Conference Topics

- LTCC / ULTCC
- 5G/6G telecommunication
- Material aspects of packaging
- Advances in modelling and characterization
- Microwave and Millimeter-wave materials
- Applications and passive components
- Advances in processing and design
- Green and sustainable materials

Organizers

Martin Letz, SCHOTT AG Mainz
Jure Demsar, JGU Mainz

For further questions and industry exhibition contact:

mma2023@uni-mainz.de

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